

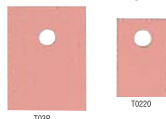
Best sellers

Sil-Pad 900S
Thermally
conductive low-pressure
insulating material



See page 676

From
£1.20

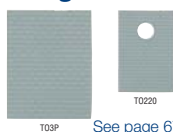


Sil-Pad 400
Thermally
conductive insulating material



See page 676

From
£0.884



E
Heat transfer paste



See page 678

From
£1.61

**Clip-on
heat sinks**



See page 678



From
£0.1196

**AAVID
THERMALLOY**
**T0220 Twisted
vane heat sink**



From
£0.38 See page 679

TruSemi
T0220 Bolt on heat sink



See page 679

From
£0.1378

Featured products

IC Extraction tool



From
£0.64 See page 682

Universal Science
T-Pad 1500



See page 676

From
£0.832



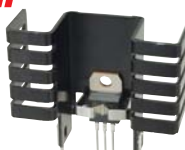
**AAVID
THERMALLOY**
**Vertical
mount
T0220 heat
sinks**



From
£1.59 See page 680

TruSemi See page 679

**T0220 Heat
sink - clip
or screw
mounting**



From
£0.3922

**AAVID
THERMALLOY**
**T0220 High
power
dissipation
type**



See page 679

From
£0.583

TruOpto
**3-lead LED
Spacer/mounts**



See page 674

From
£1.96

Heatsink	678
LED & Crystal mounts	674
Sockets	680
Thermal pads	674
Transistor mounting	677

LED & Crystal mounts

MEC

Diode mounts

Mounting blocks for wire-ended LEDs and axial lead components.

- Suitable for diodes, capacitors etc.
- LED mounting block can accept 3 or 5mm diameter LEDs and allows them to be mounted, raised from or at right angles to the PCB
- Leads are kept separated to avoid short circuits and the LED body fits into a circular recess
- The diode cradle can be used for diodes or other axial leaded components which have to be mounted vertically, due to space considerations or PCB modifications
- With components fitted in this fashion, the risk of damage to PCB tracks caused by pressure on the component is greatly reduced



38-0600



38-0605

Type	Mfrs. type	Order code	1+	25+	100+
LED Mount	LED35-80	38-0600	0.053		
Diode cradle	M201	38-0605	0.06	0.052	0.0416

RVFM

Crystal mounting pad

A plastic mounting pad for crystals with HC-49 style packages. The pads insulate the crystal case from tracks on the component side of a PCB and improve mechanical mounting stability. Because of the increased distance from the PCB, the pads also help to reduce the possibility of damage due to overheating during soldering.

- A matching mylar insulating washer is also available



Type	Order code	1+	25+	100+
Crystal mounting pad	38-0610	0.08	0.0624	0.052
Crystal insulating washer	38-0612	0.02	0.0156	0.0146

KEYSTONE

LED Spacer mounts

LED mounting spacers featuring an internally tapered barrier which guides the leads and eliminates the possibility of bending or shorting. The internal configuration also assures positive self-alignment on 2.54mm centres.

- Supplied in packs of 25



Type	Length	Order code	Price per pack of 25		
			1+	5+	10+
3mm Spacer	3.0mm	38-0750	2.24	1.92	1.79
3mm Spacer	9.1mm	38-0755	2.44	2.08	1.92
3mm Spacer	23.5mm	38-0760	2.34	1.96	1.82
5mm Spacer	3mm	38-0765	2.24	1.87	1.77
5mm Spacer	7.6mm	38-0770	2.44	2.16	1.98
5mm Spacer	12.7mm	38-0775	2.65	2.18	1.92
5mm Spacer	19mm	38-0780	2.34	2.07	2.01

Rapid newsletter

Sign up to our email newsletter for news, special offers & promotions



www.rapidonline.com/newsletter

TruOpto

3-lead LED Spacer/mounts

LED spacer mounts designed for a wide range of 3-lead LEDs providing the correct lead spacing.

- Available in a variety of standard lengths
- Supplied in packs of 25



Type	Order code	1+	5+	10+
3-lead Spacer	5.0mm 38-0338	2.29	2.12	1.96
3-lead Spacer	12.5mm 38-0346	3.07	2.81	2.55

Thermal pads

THE BERGQUIST COMPANY

Gap Pad VO Thermally conductive conformable gap-filling material

Gap Pad VO is an electrically isolating, thermally conductive interface material that, due to its conformability, will fill-in air-gaps and voids between heat-generating components and heat sinks or chassis, reducing interfacial resistance and increasing thermal transfer.

Having a reinforced carrier gives the material enhanced puncture, shear and tear resistance, whilst inherent tackiness on one side of the carrier makes handling easier. Suitable applications include: power conversion and telecommunications hardware.

- 0.8W/m-K Thermal conductivity
- Conformable for good gap-filling performance
- Rated to **UL 94V-0**
- Available in 4 x 4in sheet form in various thicknesses (see price panel for details)



Type	Thickness (in.)	Order code	1+	5+	10+
Sheet 4 x 4in	0.125	38-1040	11.49	10.92	9.67

THE BERGQUIST COMPANY

Gap Pad VO Soft Thermally conductive highly conformable gap-filling material



Gap Pad VO Soft is an electrically isolating, thermally conductive interface material that, due to its high conformability, is very efficient at filling-in air-gaps and voids between heat-generating components and heat sinks or chassis. The material is resistant to punctures, shearing and tearing, due to its carrier reinforcement, enabling better handling and, having inherent tackiness on one side, placement and conversion is made easier. The technical performance of this material make it ideally suited to applications where low application pressure is important, such as:

computers and peripherals, telecommunications, power conversion.

- 0.8W/m-K Thermal conductivity
- Highly conformable for excellent gap-filling performance
- Rated to **UL 94V-0**
- Supplied in 100 x 100mm sheet form

Type	Thickness (in.)	Order code	1+	5+	10+
Sheet 4 x 4in	0.060	38-0354	6.24	5.72	5.20

THE BERGQUIST COMPANY

Gap Pad VO Ultra Soft Thermally conductive conformable gap-filling material

Gap Pad VO Ultra Soft

is an electrically isolating, thermally conductive interface material that, because of its low hardness and low modulus design, has an ultra conformable performance that makes it ideal for applications where minimal pressure on

components is required and where a very uneven interface gap exists, air-gaps and voids being filled-in, minimising interfacial resistance and maximising thermal transfer. The viscoelastic nature of the material also gives excellent low-stress vibration dampening and shock absorbency. The materials carrier is reinforced, making handling easier and helping to protect against puncturing, tearing and shearing, and the material also has an inherent surface tack on one side which enables easier placement and conversion. Suitable applications for this material include: bare-leaded components on PCBs, high voltage devices, automotive and handheld devices.

- 1.0W/m-K Thermal conductivity
- Ultra conformable for excellent gap-filling performance
- Low Young's modulus
- Rated to **UL 94V-0**
- Available in 8 x 16in. or 4 x 4in. sheet form in various thicknesses (see price panel for details)

Type	Thickness (in.)	Order code	1+	5+	10+
Sheet 8 x 16in	0.040	38-1042	40.56		
Sheet 8 x 16in	0.080	38-1046	72.28		
Sheet 4 x 4in	0.125	38-1048	17.52	16.59	15.03

Universal Science

T-FLEX 200 gap filler

T-FLEX 200 is a very soft, freestanding gap filler that is more compressible than most gap fillers. It combines good thermal conductivity with high compressibility to produce low thermal resistance. It is electrically insulating, and is naturally tacky so does not require additional adhesive coating that can inhibit thermal performance.

- 1.1W/mK Thermal conductivity
- One-piece construction ensures maximum flexibility
- Naturally tacky needs no further adhesive coating
- Soft and compressible for low stress applications
- Available in 1, 2 and 3mm thickness (75 x 75mm)
- Temperature range -45°C to +160°C

Type	Order code	1+	5+	10+	25+
T-FLEX 200 1mm	38-3002	9.20	8.75	8.31	7.89
T-FLEX 200 2mm	38-3004	11.08	10.52	9.99	9.50
T-FLEX 200 3mm	38-3006	12.43	11.80	11.21	10.66

www.rapidonline.com

TC65T Wireless terminal starter kit



NEW



Gap Pad 2000S40 Thermally conductive gap-filling material

Gap Pad 2000S40 is a highly conformable, reinforced, gap-filling material that provides high thermal conductivity at very low mounting pressures. The material is electrically isolating and is suitable for isolation between heat sinks and bare-leaded, high voltage devices. Fibreglass reinforcement of the material enables easier handling and superior puncture, shear and tear resistance. High material conformability ensures that the material fills in air voids and gaps between heat sinks and devices.



- 2.0W/m-K Thermal conductivity
- Low thermal resistance at low mounting pressures
- Inherently tacky on both sides - aids in assembly
- Low hardness with high conformability
- Designed for low-stress applications
- Rated to **UL 94V-0**
- Available in 4 x 4in sheet form in various thicknesses (see price panel for details)

Technical specification
 Thermal conductivity 2.0W/m-K
 Heat capacity 0.61J/g-K
 Breakdown voltage >5000V AC
 Density 2.9g/cc
 Hardness (Shore 00) 30
 Operating temperature -60°C to +200°C

Type	Thickness (in)	Order code	1+	5+	10+
Sheet 4 x 4in	0.040	38-1030	23.87	22.83	20.28
Sheet 4 x 4in	0.080	38-1032	31.72	30.16	22.88
Sheet 4 x 4in	0.125	38-1034	39.00	37.44	33.28



Gap Pad 2500 Thermally conductive unreinforced gap-filling material

Gap Pad 2500 is an electrically isolating gap-filling material that features medium compliancy and conformability, which is improved by the material being unreinforced. Good wet-out and interfacing characteristics to rough and uneven surfaces also ensure high thermal transfer. The material is inherently tacky on both sides which allows for easy handling and assembly and, together with its excellent performance characteristics, make this material particularly suitable as a replacement for clip- and screw-mounted assemblies in such applications as: multiple heat generating components to a common heatsink, graphics/processor chips to heat sink interface, mass storage devices and wireless communications hardware.



- 2.7W/m-K Thermal conductivity
- High performance, cost effective solution
- Unreinforced construction for additional compliancy
- Protective liners on both sides of material
- Rated to **UL 94V-0**
- Available in 4 x 4in sheet form in various thicknesses (see price panel for details)

Technical specification
 Thermal conductivity 2.7W/m-K
 Heat capacity 1.0J/g-K
 Breakdown voltage >6000V AC
 Density 3.1g/cc
 Hardness (Shore 00) 80
 Operating temperature -60°C to +200°C

Type	Thickness (in)	Order code	1+	5+	10+
Sheet 4 x 4in	0.040	38-1024	14.51	13.47	12.43
Sheet 4 x 4in	0.125	38-1028	26.99	25.95	24.91



Gap Pad 3000S30 Thermally conductive soft gap-filling material

Gap Pad 3000S30 features high thermal performance and electrical isolation at a low mounting pressure. Having inherent tackiness on both sides of the material, as well as fibreglass carrier reinforcement, enhances material handling, puncture, shear and tear resistance. This material has been designed for high performance, low-stress applications as a replacement for standoff or clip-mounting thermal devices. Having a soft and conformable yet elastic nature ensures that, with its excellent wet-out and interfacing characteristics, an efficient thermal interface is achieved. Suitable applications for this material include: processors, server S-RAMs, mass storage devices, BGA packages, notebook computers, power conversion, wireless communications hardware.



- 3.0W/m-K Thermal conductivity
- Low thermal resistance at low mounting pressure
- Electrically isolating
- High conformability
- Double-sided tackiness and carrier reinforcement ensure easy handling and assembly
- Rated to **UL 94V-0**
- Available in 4 x 4in sheet form in various thicknesses (see price panel for details)

Technical specification
 Thermal conductivity 3.0W/m-K
 Heat capacity 1.0J/g-K
 Breakdown voltage >3000V AC
 Density 3.2g/cc
 Hardness (Shore 00) 30
 Operating temperature -60°C to +200°C

Type	Thickness (in)	Order code	1+	5+	10+
Sheet 4 x 4in	0.040	38-1030	23.87	22.83	20.28
Sheet 4 x 4in	0.080	38-1032	31.72	30.16	22.88
Sheet 4 x 4in	0.125	38-1034	39.00	37.44	33.28



Gap Pad 5000S35 Thermally conductive high performance gap-filling material

Gap Pad 5000S35 is an electrically isolating, gap-filling material that features exceptionally high thermal performance at low mounting pressures, reinforced carrier for easy handling and converting, and high conformability to reduce interfacial resistance. The material is inherently tacky on both sides and has very soft characteristics, whilst maintaining elasticity, that enables it to conform to demanding contours and maintain structural integrity with little or no stress applied to fragile components. Typical applications include: memory packages/modules, voltage regulator modules, PC board to chassis, thermally enhanced BGAs, ASICs to DSPs.



- 5.0W/m-K Thermal conductivity
- Soft and highly conformable
- Fibreglass reinforced for puncture, shear and rear resistance
- Electrically isolating
- Rated to **UL 94V-0**
- Available in 8 x 16in sheet form in 1.52mm (0.06in) thickness

Technical specification
 Thermal conductivity 5.0W/m-K
 Heat capacity 1.0J/g-K
 Breakdown voltage >5000V AC
 Density 3.6g/cc
 Hardness (Shore 00) 35
 Operating temperature -60°C to +200°C

Type	Thickness (in)	Order code	1+
Sheet 8 x 16in	0.060	38-1036	99.84



Free delivery
 on all orders over £30
 (excl. VAT)
 (UK mainland only)

www.rapidonline.com

Evaluation board & mini evaluation kit



NEW



Hi-Flow 625 Thermally conductive phase-change interface material

Flexible Hi-Flow is a phase-change material on an insulating substrate designed specifically to replace grease as a thermal interface. At



+65°C Hi-Flow changes from a solid and flows (phase-change temperature) thereby assuring total wet-out of the interface. The thixotropic characteristics of the material prevent it from flowing out of the interface when mounted vertically. The result is a thermal interface without the mess and other problems associated with grease.

- 0.4W/m-K Thermal conductivity
- Supplied in packs of 10 pads to suit TO-220 and TO-3P devices and also in 4 x 4in sheet form

Technical specification
 Breakdown voltage 4kV
 Thermal conductivity 0.4W/m-K
 Thermal resistance 0.25°C/W
 Thickness of substrate 0.127mm (0.005in)
 Phase-change temperature 65°C
 Operating temperature -30°C to +150°C

Type	Overall dimensions (mm)	Fixing hole dia.	Order code
TO-220	19.05 x 12.7	3.7	38-0400
TO-3P	25.4 x 19.1	3.6	38-0402

Type	Pack quantity	Order code	1+	10+	50+
TO-220	10	38-0400	1.66	1.46	1.18
TO-3P	10	38-0402	1.87	1.66	1.46



Hi-Flow 300P Thermally conductive phase-change interface material

Hi-Flow 300P consists of a high performance phase-change compound, coated on a thermally conductive and electrically isolating carrier, that is designed as a replacement for grease as a thermal interface. At a lower phase-change temperature of +55°C the material changes from a solid and flows, thereby assuring total wet-out of the interface. The thixotropic characteristics of the material prevent it from flowing out of the interface, giving a thermal performance comparable to grease but without the associated handling problems.



- 1.6W/m-K Thermal conductivity
- Phase-change temperature +55°C
- Electrically isolating
- Tack free
- Scratch resistance at room temperature
- Rated to **UL 94V-0**
- Supplied in 4 x 4in sheet form in 0.015in thickness

Technical specification
 Thermal conductivity 1.6W/m-K
 Breakdown voltage 5000V AC
 Phase-change temperature +55°C
 Continuous use temperature +150°C

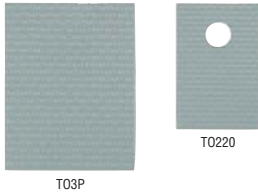
Type	Thickness (in)	Order code	1+	10+	50+
Sheet 4 x 4in	0.015	38-1052	5.88	5.30	4.11



Sil-Pad 400 Thermally conductive insulating material

An economic material designed to replace grease and mica for power applications. Ideal in reducing assembly time and maintaining cleanliness in production environments. Consists of a glass fibre sheet coated with a thermally conductive silicon elastomer. Available in a variety of semiconductor styles - with or without adhesive backing - and also in 12 x 12in sheet form.

- 0.9W/m-K Thermal conductivity



Technical specification	
Breakdown voltage	3500V AC
Thickness	0.177mm (0.007in)
Thermal conductivity	0.9W/m-K
Operating temperature	-60°C to +180°C
Thermal resistance	0.40°C/W

Type	Overall dimensions (mm)	Fixing hole dia.	Pack quantity	Order code
Adhesive-backed				
TO-220	19.05 x 12.7	3.7	22	38-0428
Non-adhesive				
TO-220	19.05 x 12.7	3.7	10	38-1068
TO-220	(no hole) 19.05 x 12.7	-	10	38-1066
TO-3P	25.4 x 19.1	3.6	10	38-1064
Sheet	305 x 305 (12 x 12in)	-	-	38-1062

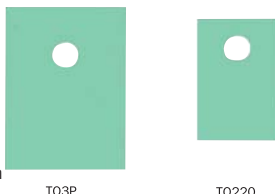
Type	Pack qty	Order code	1+	10+	50+
Adhesive-backed					
TO-220	22	38-0428	2.39	2.18	2.07
Non-adhesive					
TO-220	10	38-1068	1.61	1.40	1.14
TO-220 (no hole)	10	38-1066	1.25	1.07	0.884
TO-3P	10	38-1064	1.40	1.20	1.03
Type		Order code	1+	5+	10+
Sheet 12 x 12in	-	38-1062	10.76	10.14	9.31



Sil-Pad K6 Thermally conductive puncture resistant insulating material

Designed to resist puncturing due to burrs or high pressures when mounting semiconductor devices to heatsinks. Constructed from Kapton and a thermally conductive elastomer coating loaded with aluminium oxide/boron nitride applied to both sides, K6 couples high dielectric strength with a no grease, no mess method of assembly.

- 1.1W/m-K Thermal conductivity
- Available to fit TO-3P, TO-220 and also in 12 x 12in sheet form



Technical specification	
Breakdown voltage	6000V AC
Thermal conductivity	1.1W/m-K
Thermal resistance	0.30°C/W (TO3)
Thickness	0.15mm (0.006in)
Operating temperature	-60°C to +180°C

Type	Overall dimensions (mm)	Fixing hole dia. (mm)	Order code
TO-3P	25.4 x 19.1	3.6	38-0380
TO-220	19.05 x 12.7	3.7	38-0375
Sheet	305 x 305 (12 x 12in)	-	38-1084

Type	Pack quantity	Order code	1+	10+	50+
TO-3P	10	38-0380	4.77	4.67	4.54
TO-220	10	38-0375	2.03	1.87	1.82
Sheet 12 x 12in	-	38-1084	21.58		



Sil-Pad K-10 Thermally conductive puncture-resistant insulating material

Sil-Pad K-10 is a high performance Kapton-based insulator that combines a special film with a filled silicone rubber. The result is a thermal pad with excellent electrical performance that is puncture resistant and has good mechanical properties.

- 1.3W/m-K Thermal conductivity
- Available in TO-220 and TO-3P styles and also in 12 x 12in. sheet form



Technical specification	
Thermal conductivity	1.3W/m-K
Thermal resistance	2.01°C/W
Thickness of substrate	0.15mm (0.006in.)
Operating temperature	-60°C to +180°C

Type	Overall dimensions (mm)	Fixing hole dia.	Order code
TO-220	19.05 x 12.7	3.7	38-0220
TO-3P	25.4 x 19.1	3.6	38-1080
Sheet	305 x 305 (12 x 12in.)	-	38-1082

Type	Pack quantity	Order code	1+	10+	50+
TO-220	10	38-0220	2.60	2.39	2.29
TO-3P	5	38-1080	2.18	1.98	1.82
Sheet 12 x 12in	-	38-1082	39.00		

Universal Science

T-Pad 1500

T-Pad 1500 is a soft thermal interface pad designed to provide good thermal resistance and high dielectric strength while remaining cost effective.

- 1.5W/mK Thermal conductivity
- Electrically isolating
- Enhances the heat flow from electronic components to heat sink
- Fiber glass reinforcement provides a rugged and strong interface material to maintain electrical isolation in the application
- Pads supplied in packs of 10



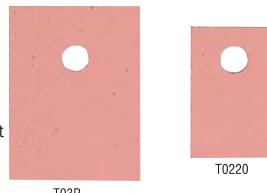
Technical specification	
Colour	Yellow
Thickness	0.23mm
Thermal conductivity	1.5W/mK
Specific gravity	1.6
Heat capacity	1.3J/g.K
Hardness	75 ±5 Shore
Continuous use temp	-40°C to +200°C
Tensile strength	>19.3N/mm
Tear strength	>6.6N/mm
Elongation	8-12%
Young's Modulus	310KPa
Dielectric breakdown voltage	>6kV
Dielectric constant	6
Thermal impedance	2.9K-cm ² /W
	0.44K-in ² /W
Volume resistivity	10 ¹¹ Ohm.cm
Flame rating	UL94 V-0

Price per pack of 10						
Type	Pack qty	Order code	1+	25+	100+	250+
100 x 100mm	1x Sheet	38-3034	8.84	8.32	7.28	6.24
TO-3P Pad	10	38-3038	1.13	1.04	0.936	0.832



Sil-Pad 900S Thermally conductive low-pressure insulating material

A high performance thermally conductive material, with or without a thermally efficient adhesive, for applications requiring high thermal conductivity. The pads can be applied to either the heatsink or the device and are specifically designed for low mounting pressure applications.



- 1.6W/m-K Thermal conductivity
- Clip-mount pads have no fixing holes
- Available to suit various semiconductor package profiles and in 4 x 4in. sheet form

Technical specification	
Breakdown voltage	5.5KV AC
Thermal conductivity	1.6W/m-K
Thermal resistance	0.2°C/W
Thickness	0.23mm (0.009in.)

Type	Overall dimensions (mm)	Fixing hole dia. (mm)	Order code
Adhesive-backed			
TO-220	19.05 x 12.7	3.7	38-1002
TO-220 clip-mount	19.05 x 12.7	-	38-1003
TO-3P	25.4 x 19.1	3.6	38-1006
Non-adhesive			
TO-220	19.05 x 12.7	3.7	38-1074
TO-3P	25.4 x 19.1	3.6	38-1072
Sheet	102 x 102 (4 x 4in.)	-	38-1070

Type	Pack qty	Order code	1+	10+	50+	100+
Adhesive-backed						
TO-220	10	38-1002	1.56	1.46	1.35	1.25
TO-220 Clip-mount	10	38-1003	1.56	1.46	1.35	1.25
TO-3P	10	38-1006	1.76	1.61	1.56	1.45
Non-adhesive						
TO-220	10	38-1074	1.60	1.40	1.30	1.20
TO-3P	10	38-1072	1.92	1.66	1.56	1.46
Sheet 4 x 4in	-	38-1070	4.42	3.80	3.17	



Sil-Pad A1500 Thermally conductive insulator material

Sil-Pad 1500 is a high performance thermally conductive, electrically insulating material that consists of a fiberglass reinforcement carrier coated on both sides with a cured silicone elastomeric compound. The combination of high thermal performance, compliance and durability make it suitable for applications requiring electrical isolation and cut-through resistance such as: power supplies, automotive electronics, motor controls, power semiconductors.

- 2.0W/m-K Thermal conductivity
- Excellent performance at up to 200psi mounting pressure
- Rated to **UL 94V-0**
- Cut to 12 x 12in sheet form in 0.010in thickness



Technical specification	
Thermal conductivity	2.0W/m-K
Thermal impedance (@ 50psi mounting pressure)	0.42°C-in ² /W
Hardness (Shore A)	80
Breakdown voltage	6000V AC
Operating temperature	-60°C to +180°C

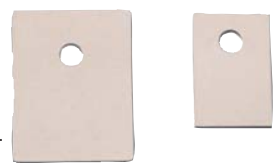
Type	Thickness (in)	Order code	1+
Sheet 12 x 12in	0.010	38-1076	65.00



Sil-Pad 2000 Thermally conductive high performance insulating material

Thermal transfer material which offers vastly improved performance over normal thermal transfer materials.

- 3.5W/m-K Thermal conductivity
- Suitable for applications demanding extremely efficient heat transfer such as military, medical or aerospace, or for high reliability electronics where junction devices of integrated circuits are critical



Technical specification	
Breakdown voltage	4000V AC
Thickness	0.38mm (0.015in)
Thermal conductivity	3.5W/m-K
Operating temperature	-60°C to +200°C
Thermal resistance (TO-3)	0.20°C/W

Type	Overall dimensions (mm)	Fixing hole dia.	Order code
TO-220	19.05 x 12.7	3.7	38-0475
TO-3P	25.4 x 19.1	3.6	38-0480
Sheet	152 x 152 (6 x 6in)	-	38-1060

Type	Pack qty	Order code	1+	10+	50+
TO-220	10	38-0475	3.90	3.64	3.33
TO-3P	10	38-0480	6.08	5.62	5.41

Fast & friendly service



Call now 8am to 8pm
Monday to Friday;
9am to 5pm Saturday

01206 751166

Universal Science
T-Pad 6000 Ultra thermally conductive pad

The T-Pad 6000 thermal pad is the ultimate performer in thermal conduction and electrical isolation. Featuring 5W/mK of thermal conductivity this pad has been designed for demanding applications where heat needs to be transferred from electronic devices to heat sinks or cold walls. Its rugged, puncture and tear-resistant construction gives excellent dielectric properties for medium and high voltage applications in power conversion, automotive, aerospace, motor drives as well as mounting FETs and other power devices to heatsinks.

- 5W/mK Thermal conductivity
- High thermal conductivity and high electrical isolation
- Flammability rating **UL 94-V0**
- Supplied in **177 x 203mm** or **356 x 406mm** sheets or pre-cut pads in **packs of 10**

Technical specification	
Colour	White
Thickness	0.25mm
Thermal conductivity	5W/mK
Thermal impedance	1.17K-cm ² /W
Density	1.52
Continuous use temperature range	-60°C to +200°C
Hardness	85 Shore A
Dielectric breakdown	6000V
Dielectric constant	3.32
Volume resistivity	5 x 10 ¹³ Ω/cm

Type	Size	Order code	1+	25+	100+	250+
Sheet	177 x 203mm	38-3059	15.97	14.61	12.58	11.44
Sheet	356 x 406mm	38-3064	48.36			
T0-220	Pack of 10	38-3060	2.76	2.60	2.34	2.13
T0-3P	Pack of 10	38-3062	4.00	3.80	3.43	3.07



Q-Pad 3 Thermally conductive non-insulating grease replacement material

Q-Pad 3 is a material that has been designed as a thermally conductive grease replacement in applications where electrical insulation is not required. The material eliminates the handling and processing problems associated with grease such as solder bath contamination and board cleaning issues but still gives excellent thermal performance. A fibreglass reinforced carrier provides ease of handling and protects against processing stresses whilst still allowing the material to conform to uneven surfaces thereby reducing air-gaps and voids and lowering interfacial resistance.

- 2.0W/m-K Thermal conductivity
- Performance of grease without the processing constraints
- Reinforced for easy handling and processing protection
- May be installed prior to soldering and washing
- Rated to **UL 94V-0**
- Supplied in 4 x 4in sheet form in 0.005in thickness

Technical specification	
Thermal conductivity	2.0W/m-K
Thermal impedance (@ 50psi mounting pressure)	0.35°C-in ² /W
Hardness (Shore A)	86
Operating temperature	-60°C to +180°C

Type	Thickness (in)	Order code	1+	10+	50+
Sheet 4 x 4in	0.005	38-1056	2.34	2.18	2.08

www.rapidonline.com

Tactile switches
6 x 6mm

A range of miniature through hole tactile switches



NEW



Bond-Ply 100 Thermally conductive adhesive material

Bond-Ply 100 is a thermally conductive and electrically isolating, pressure sensitive adhesive material that facilitates the decoupling of materials with mismatched thermal coefficients of expansion. The double-sided adhesive coating with its high bond strength that immediately bonds to the target surface, together with excellent wet-out and high thermal performance, make this material ideally suited to use as a replacement for heat-cure adhesive and screw- or clip-mounting solutions

- 0.86W/m-K Thermal conductivity
- Bond strength increases over time
- Rated to **UL 94V-0**
- Available in various sheet sizes (see price panel for details)

Technical specification	
Thermal conductivity	0.8W/m-K
Thermal resistance @ 100psi	0.55°C-in ² /W
Breakdown voltage	3000V AC
Operating temperature	-30°C to +120°C
Thickness	0.127mm (0.005in)
Lap shear @ Rr	0.7MPa (100psi)

Type	Pack qty	Order code	1+	10+	25+
Sheet 1 x 1in	10	38-1010	2.29	2.08	1.82
Sheet 12 x 12in	-	38-1012	20.80	18.72	15.60
Sheet 6x 6in	-	38-1014	7.12	5.88	4.99

Transistor mounting



Transistor holders

Printed circuit mounting transistor sockets.

- Moulded in thermoplastic
- Gold flashed contacts
- Temperature range -176°C to +150°C



Type	Order code	1+	100+	500+
3-pin T018	22-0100	0.49	0.45	0.416
3-pin T05	22-0105	0.31	0.2392	0.2184



Silicone rubber mounting kits



Silicone rubber, insulated mounting kits for T03 and T0220 devices, consisting of a silicone rubber pad and insulating washers (two for T03 and one for T0220). The pads are constructed from thermally conductive silicone rubber compound coated on to a layer of woven glassfibre to provide a strong, flexible and clean insulator. Faster assembly times can be achieved over mica, as there is no need to use messy and time-consuming heatsink compounds.

- Flame retardant to UL94V-0
- Supplied in **packs of 10** or **packs of 1000 kits**

Technical specification	
Breakdown voltage (50Hz)	3500V
Thermal resistance (T03)	Approx. 0.45°/Watt
Thermal conductivity	0.79Wm-1K-1
Temperature range	-60°C to +180°C

Price per pack of 10					
Type	Order code	1+	25+	100+	250+
T03 Mounting kit	38-0240	1.56	1.51	1.46	1.40
T0220 Mount. kit (0.230mm)	38-0246	0.95	0.75	0.65	0.62

Price per pack of 1000					
Type	Order code	1+	5+	10+	
T0220 mount. kit (0.230mm)	38-0249	75.00	65.00	55.00	

www.rapidonline.com

NEW



APU501 Application board for mini evaluation kit



T0-220 Kits

Kit contents 10 mica washers and 10 bushes.

- To suit TIP31A, 7805, etc.
- M3 clearance for screws



Type	Order code	1+	25+	100+
10 T0220 Kits type 1	38-0210	0.68	0.6136	0.5824



T0-220 kits type 2

Kit contents 10 mica washers and 10 bushes.

- To suit TIP31A, 7805, etc.
- M3 clearance for screws
- Dimensions 15 x 19mm



Type	Order code	1+	25+	100+
10 T0220 Kits type 2	38-0212	0.68	0.6136	0.5824



T0-218 Kits

Kit contents 10 mica washers and 10 bushes.

- To suit TIP3055, etc.



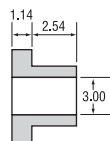
Type	Order code	1+	25+	100+
10 MI3055 Kits	38-0215	0.66	0.6136	0.5928



Insulating bushes

Nylon insulating bushes for use with screw mounted transistors. Used in conjunction with mica or other insulating thermal pads to electrically isolate transistors from heatsinks.

- M3 clearance for screws
- Supplied in **packs of 10**



T0220

Price per pack of 10				
Type	Order code	1+	25+	100+
T0-220	38-0230	0.60	0.4576	0.3536



Heatsink compound

A silicone based product for use on heat sinks, transistors and other semiconductors.



- Maintains a positive heatsink seal
- Excellent thermal conductivity
- Non flammable
- High thermal stability
- Working temperature range -50°C to +200°C
- Supplied in **25g tube**

Type	Order code	1+	10+	25+
25g Heatsink compound	87-1130	2.59	2.38	2.07

Page 682

IC Extraction tool



Heat transfer paste

A non-melting, non-hardening compound with high thermal conductivity for thermal coupling of components.

- Ideal for use with medium to high power semiconductors and heatsinks
- The compound formulation is silicone-free
- **Electrolube type HTC02S (2ml) HTC35L (35ml)**

Technical specification
 Temperature range -200°C to +130°C
 Dielectric strength 42kV/mm

Type	Order code	1+	10+	30+	60+
2ml Syringe	36-0400	2.03	1.82	1.72	1.61
35ml Syringe	36-0405	5.40	5.25	5.15	4.94



Non-silicone heatsink compound



An efficient heat-transfer compound, suitable for use on most resistors, semiconductors, heatsinks, etc. The non-silicone formulation removes problems like high contact resistance and soldering difficulties, which can be caused by silicone contamination.

- Temperature range: -50°C to +130°C
- Supplied in a range of syringe sizes for easy, pin-point application and minimisation of waste

Type	Order code	1+	10+	20+	40+
2ml Syringe	36-0390	2.54	1.99	1.88	1.79
10ml Syringe	36-0392	3.63	3.07	2.96	2.86
35ml Syringe	36-0394	6.19	5.71	5.61	5.50



Spring mounting clips

An easy and convenient method of mounting power devices, the clips apply an even pressure across the body of the device improving the devices thermal transfer characteristics.

- Zinc plated, clear passivated finish
- Clips available to suit TO3P, TO218 and TO247 packages

Type	Order code	1+
TO3P, TO218, TO247	38-0965	0.035



TO-220 mounting clip

Single hole fixing mounting clip for TO-220 devices.

- Available for mounting either one or two devices

Type	Order code	1+	25+	100+	500+
TO220 Single clip	38-0332	0.44	0.3952	0.3744	0.3432
TO220 Double clip	38-0334	0.44	0.4056	0.364	0.3432



TO-3 transistor cover

A push fit protective TO-3 plastic cover.



Type	Order code	1+	25+	100+	500+
TO3 Cover	38-0330	0.16	0.1144	0.104	0.0936

Heatsink



TO-5 Heatsink

A low cost push-on heat sink that is suitable for TO-5 package components.

- 45.2°C/W Thermal resistance
- Black anodised finish



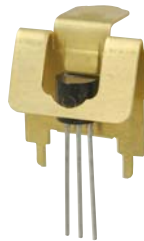
Type	Order code	1+	25+	100+	500+
TO-5 Heatsink	36-0256	0.31	0.2912	0.26	0.2132



TO-92 Heatsink

A low cost, brass clip-on heatsink that is suitable for TO-92 package components.

- 36.1°C/W Thermal resistance



Note: Transistor shown in image is not supplied.

Type	Order code	1+	25+	100+	500+
TO-92 Heatsink	36-0258	0.23	0.208	0.1872	0.1508



SOT-32 vertical twisted vane

A compact, twisted vane heatsink.

- Pre-drilled to accommodate a single SOT-32 package
- Thermal resistance is 21.6°C/W
- Dimensions 22 x 19 x 19mm



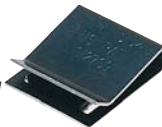
Type	Order code	1+	25+	100+	500+
Type TV4 SOT32	36-0198	0.414	0.37	0.32	0.265



Clip-on TO-220 heatsink

A clip-on heatsink to fit a single TO-220 package.

- Black pre-anodised finish with bare edges
- Thermal resistance is 23°C/W
- Dimensions 20.3 x 6.8 x 25.4mm



Type	Order code	1+	25+	100+	500+
Type 6043PB	36-0304	0.28	0.26	0.2184	0.1768



Fast delivery

All orders received by 8pm - Monday to Friday are despatched the same day

www.rapidonline.com

TO-220 Power MOSFETs

A range of standard power MOSFETs supplied in TO-220 packages



TO-220 Clip on heat sinks

Miniature clip on heat sinks suitable for use with TO-220 packages.

- Available also with solderable mounting lug to improve mechanical stability

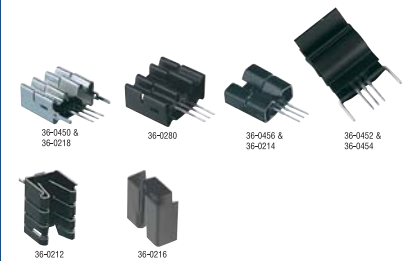


Note: Component shown in image is not supplied.

Type	Order code	1+	25+	100+	500+
TO220 clip on 20°C/W	36-0285	0.30	0.1908	0.1272	0.1007
TO220 with lug 20°C/W	36-0290	0.33	0.2756	0.2332	0.1484



Clip-on heat sinks



A range of clip-on heat sinks.

- For TO220, TO251, TO252, TO202, TO126 and SOT23 packages
- To cover vertical or horizontal mounting arrangements
- To suit applications with and without solderable fixing lugs

Type	Thermal resistance	With lugs	Dimensions (W x D x H) mm	Mounting	Order code
HF35	11°C/W	yes	35 x 20 x 28	V	36-0454
PF758	17.3°C/W	yes	22 x 11 x 24	V	36-0218
PF750	20.3°C/W	yes	22 x 11 x 19	V	36-0450
PF745	23.1°C/W	no	21.8 x 10 x 19.1	V & H	36-0216
PF752	23.7°C/W	no	22 x 11 x 19	V	36-0280
PF436	25.3°C/W	yes	12.7 x 12.7 x 19.5	H	36-0212
PF720	28.9°C/W	no	19.7 x 20 x 8.1	V	36-0456
PF730	35.8°C/W	no	19.7 x 8.1 x 13.2	V	36-0214*

Type	Order code	1+	25+	100+	500+
Type HF35	36-0454	0.714			
Type PF758	36-0218	0.72	0.6136	0.572	0.5096
Type PF750	36-0450	0.61	0.5096	0.4784	0.4576
Type PF745	36-0216	0.46	0.4056	0.3328	0.2808
Type PF752	36-0280	0.36	0.3016	0.2392	0.2236
Type PF436	36-0212	0.29	0.1872	0.1768	0.1664
Type PF720	36-0456	0.23	0.1872	0.156	0.1196
Type PF730	36-0214	0.25	0.2184	0.1768	0.1456



TO220 High power dissipation type

A range of compact, high power dissipation, vertical mounting extruded heat sinks with solderable fixing pins.

- Designed to accommodate a single TO220 package either via a separate clip, or by a mounting hole
- All the heat sinks have the same cross-section of 35 x 25.4mm with different heights for the relevant thermal resistance
- Fixing lugs are on a standard 25.4mm pitch



Technical specification	Type	Thermal resistance	Height	Device mounting	Order code
BW38-4	7.3°C/W	38mm	Hole	36-0202	
BW50-2	5.9°C/W	50mm	Hole	36-0204	
BW50-4	5.9°C/W	50mm	Clip	36-0206	
6801	matching fixing clip			36-0308	

Type	Order code	1+	25+	100+	500+
Type BW38-4	36-0202	1.03	0.988	0.884	0.8216
Type BW50-2	36-0204	0.583			
Type BW50-4	36-0206	1.36	1.16	1.04	0.988
6801 Clip	36-0308	0.067			



Compact vertical TO220/TO218/TO247 heat sink

A range of compact, vertical mounting extruded heat sinks with solderable fixing pins.

- Designed to accommodate a single TO220/TO218/TO2457 package either via a separate clip, or by mounting holes
- All the heat sinks have the same cross-section of 34.5 x 12.5mm with different heights for the relevant thermal resistance
- Fixing lugs are on a standard 25.4mm pitch



Technical specification	Type	Thermal resistance	Height	Device mounting	Order code
SW25-2	11.4°C/W	25mm	clip	36-0220	
SW25-4	11.4°C/W	25mm	2 x holes	36-0222	
SW38-4	10.2°C/W	38mm	3 x holes	36-0226	
SW50-2	8.8°C/W	50mm	clip	36-0228	
SW50-4	8.8°C/W	50mm	3 x holes	36-0190	
5901	matching fixing clip			36-0446	

Type	Order code	1+	25+	100+	500+
Type SW25-2	36-0220	0.61	0.5408	0.4576	0.3848
Type SW25-4	36-0222	0.52	0.4472	0.3848	0.3224
Type SW38-4	36-0226	0.77	0.6448	0.5512	0.4784
Type SW50-2	36-0228	0.80	0.69	0.60	0.49
Type SW50-4	36-0190	0.81	0.78	0.68	0.588
5901 Clip	36-0446	0.13	0.0954	0.0901	0.0795



TO220 Twisted vane heat sink

A high dissipation twisted vane heat sink.

- Black anodised finished
- Pre-drilled for a variety of plastic packaged semiconductors
- May be mounted horizontally or vertically



Technical specification	Type	Thermal resistance	Dimensions	AAVID part
9.9°C/W			38 x 28 x 22 (H)	TV40

Type	Order code	1+	25+	100+	500+
Twisted vane TO220	36-0250	0.52	0.49	0.45	0.38



TO220 Twisted vane heat sinks

A range of twisted vane heat sinks.

- Pre-drilled for either one or two TO220 packages in either horizontal or vertical mounting



Technical specification	Type	Thermal resistance	Mounting	+ no. of devices	Dimensions (W x D x H)	Order code
TV58	29.9°C/W	horiz - one			22 x 19 x 11mm	36-0180
TV47	27.1°C/W	horiz - one			22 x 19 x 13mm	36-0182
TV5	21.6°C/W	horiz - one			22 x 19 x 19mm	36-0184
TV1505	17.0°C/W	vert./lugs - one			24.1 x 12.7 x 30.2mm	36-0194
5900PB	17.0°C/W	vert./lugs - one			24.1 x 12.7 x 30.2mm	36-0300
TV35	7.2°C/W	horiz - one			42 x 38 x 25mm	36-0196

Type	Order code	1+	25+	100+	500+
Type TV58	36-0180	0.62	0.4992	0.3848	0.3016
Type TV47	36-0182	1.20	0.97	0.86	0.78
Type TV5	36-0184	0.68	0.5096	0.4056	0.3744
Type TV1505	36-0194	0.41	0.364	0.312	0.26
Type 5900PB	36-0300	0.33	0.3016	0.26	0.234
Type TV35	36-0196	0.73	0.624	0.5928	0.5616



Low cost TO220 heat sink

A low cost heat sink pre-drilled to accommodate a single TO220 package.

- Black pre-anodised finish with bare edges
- Thermal resistance is 21.0°C



Type	Order code	1+	25+	100+	500+
Type 6073PB	36-0306	0.25	0.2184	0.1768	0.1456



TO220 Vertical mounting heat sink

Black anodised pre-drilled heat sink complete with tinned solderable mounting lugs for vastly improved mechanical stability.

- Designed specifically for use in an upright position



Technical specification	Type	Thermal resistance	Dimensions	Order code
TO220 vertical		21°C/W	31 x 22 x 5mm	36-0240

Type	Order code	1+
Vertical TO220	36-0240	0.086



TO220 Heat sink with lugs

Black anodised pre-drilled heat sink complete with tinned solderable mounting lugs for vastly improved mechanical stability and reduced assembly time.



Technical specification	Type	Thermal resistance	Dimensions	Order code
TO220 with lug		19°C/W	25 x 30 x 12.7mm	36-0235

Type	Order code	1+	25+	100+	500+
25 x 30 x 12.7mm	36-0235	0.52	0.424	0.3604	0.2915



TO220 Bolt on heat sink

Black anodised pre-drilled heat sink to accept a wide variety of TO220 packaged semiconductors, i.e. voltage regulators and power transistors.

- May be mounted horizontally or vertically



Technical specification	Type	Thermal resistance	Dimensions	Order code
21°C/W			9.5 x 19.1 x 19.1mm	36-0115

Type	Order code	1+	25+	100+	1000+
TO220 Bolt on sink	36-0115	0.23	0.1866	0.1579	0.1378



TO220 Bolt on heat sink 21.6mm fins

Black anodised pre-drilled heat sink to accept a wide variety of TO220 packaged semiconductors i.e. voltage regulators and power transistors.

- May be mounted vertically or horizontally



Technical specification	Type	Thermal resistance	Dimensions	Order code
TO220		17°C/W	19.8 x 17.8 x 21.6	36-0150

Type	Order code	1+	25+	100+	500+
TO220 Bolt on	36-0150	0.32	0.2332	0.2014	0.1696



TO220 Heat sink 10.5°C/W

A pre-drilled black anodised heat sink suitable for TO220 packages.

- Solderable PCB mounting tags improve mechanical stability



Technical specification	Type	Thermal resistance	Dimensions	Order code
TO220		10.5°C/W	42.5 x 25.4 x 25.4	36-0170

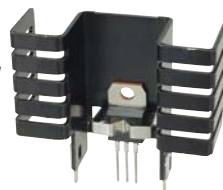
Type	Order code	1+	25+	100+	500+
TO220 Heatsink	36-0170	0.35	0.2968	0.2226	0.1802



TO220 Heat sink - clip or screw mounting

A black anodised heat sink which can be mounted to the TO220 package either by screw or clip.

- Screw hole and slots on heat sink offer fixing via screw or clips
- Tags on the base of the heat sink can be soldered to board for added stability
- Clip supplied separately - see below



Technical specification	Type	Thermal resistance	Dimensions	Order code
TO220		7.8°C/W	51 x 41 x 18.5mm	36-0252

Type	Order code	1+	25+	100+	500+
TO220 Heatsink	36-0252	0.65	0.53	0.4664	0.3922
Mounting clip	36-0254	0.08	0.0636	0.0509	0.0424

Returns
To return an item download a returns form from www.rapidonline.com/returns

Special offers
Find all the latest prices and special offers www.rapidonline.com/offers



TO220 Heat sinks with lugs

Black anodised heat sinks suitable for TO220 and TO218 packages with solderable tabs (2.6mm dia.) on 25.4mm centres.

- Devices are clip mounted to the heat sink significantly reducing assembly time



Technical specification						
Thermal resistance	Dimensions (w x h x d)	Order code	1+	25+	100+	500+
13°C/W	34.5 x 25 x 12.5	36-0440				
10°C/W	34.5 x 38 x 12.5	36-0442				
8.6°C/W	34.5 x 50 x 12.5	36-0444				
Type	Order code	1+	25+	100+	500+	
13°C/W Sink	36-0440	0.66	0.5724	0.477	0.4134	
10°C/W Sink	36-0442	0.84	0.636	0.5618	0.4452	
8.6°C/W Sink	36-0444	0.89	0.689	0.5936	0.5088	
5901 Clip	36-0446	0.13	0.0954	0.0901	0.0795	



High power dissipation heat sink



These high power dissipation, extruded heat sinks have been designed to accommodate one or more TO220 packages.

- Can also be used with TO218 and TO3P types
- Suitable securing clips are available separately, please see below
- Type **KL100-1** has a threaded slot to accommodate a TO220 if preferred
- The heat sinks are designed to minimise board space, with a threaded slot in the base to aid assembly

Technical specification							
Type	Thermal resistance	Dimensions (H x W x D)	Order code	1+	10+	50+	100+
KL100-1	3.4°C/W	28 x 50 x 100mm	36-0298				
KM100-1	3.3°C/W	45 x 30 x 100mm	36-0210				
KM75-1	3.7°C/W	45 x 30 x 75mm	36-0318				
4426	Clip for TO220 with lugs		36-0296				
4525	Clip for TO220 no lugs for space saving		36-0298				
Type	Order code	1+	10+	50+	100+		
KL100-1 Heatsink	36-0298	3.31	2.97	2.58	2.06		
KM100-1 Heatsink	36-0210	3.11	2.86	2.39	1.85		
KM75-1 Heatsink	36-0318	2.76	2.03	1.82	1.70		
Clip for TO220 with lugs	36-0296	0.10	0.0926	0.078	0.0686		
Clip for TO220	36-0298	0.09	0.0822	0.0718	0.0614		

High power dissipation



This extruded heat sink is pre-drilled to accommodate a single TO220 package.

- Suitable for vertical or horizontal mounting
- Central groove prevents device rotation
- Thermal resistance is 6.8°C/W (horizontal) and 8.8°C/W (vertical)
- Dimensions 60 x 32 x 16mm

Type	Order code	1+	10+	50+
Type 1.25GY-50	36-0292	2.06	1.87	1.64



Vertical mount TO220 heat sinks

A range of vertical mounting, extruded aluminium heat sinks with solderable fixing lugs.

- Designed to accommodate a single TO220 package
- Type **6298B** has cuts at the base of the heat sink



Technical specification			
Type	Thermal resistance (W x D x H)	Dimensions (W x D x H)	Order code
6396B	5.6°C/W	41.9 x 25.4 x 25.4mm	36-0314
6298B	3.9°C/W	41.9 x 25.4 x 38.1mm	36-0316

The solderable lugs are on a 25.4mm pitch

Type	Order code	1+	10+	50+	100+
6396B	36-0314	2.28	2.03	1.86	1.59
6298B	36-0316	2.50	2.08	1.87	1.61



TO220 Heat sink 12.5°C/W

A predrilled black anodised heat sink for use with either one or two TO220 packages.

- Compact space saving design



Technical specification							
Type	Thermal resistance	Dimensions	Order code	1+	25+	100+	500+
TO220	12.5°C/W	37 x 21.6 x 19.8mm	36-0140				
Type	Order code	1+	25+	100+	500+		
Twin TO220	36-0140	0.45	0.3604	0.318	0.2544		



Heavy duty heat sink

Suitable for high power applications with integral tee-slots.

- Black anodised finish



Technical specification			
Thermal resistance	Dimensions	Aavid part.	
1.1°C/W	152 x 130 x 32	6W1	
Type	Order code	1+	10+
Heavy duty sink	36-0125	7.80	6.86



TO-3 Heat sink

A low cost, diamond shaped heat sink that is suitable for TO-3 package components.

- 7.4C/W Thermal resistance
- Black anodised finish



Type	Order code	1+	25+	100+	500+
TO-3 Heatsink	36-0260	7.49	6.95	6.20	5.69



TO3 Twisted vane

A compact horizontal or vertical mounting heat sink.

- Pre-drilled for TO3 devices
- Black anodised finish



Technical specification					
Thermal resistance	Dimensions	Aavid part.			
7.1°C/W	42 x 38 x 25 (h)	TV3			
Type	Order code	1+	25+	100+	500+
Twisted vane TO3	36-0230	0.68	0.6136	0.572	0.4888



DPAK/D²PAK SMT Heat sinks

Surface mount copper heat sinks, with solderable finish.

- Designed for use with a single DPAK or D²PAK package



Technical specification						
Thermal resistance	Dimensions (W x D x H)	Order code				
15.0°C/W	25.9 x 15 x 9.5	36-0160				
11.0°C/W	25.4 x 19.4 x 11.4	36-0162				
Type	Package	Order code	1+	25+	100+	500+
7106DG	DPAK	36-0160	0.60	0.5096	0.4368	0.3744

Sockets



Wirewrap turned pin 2.54mm SIL sockets

Professional quality turned pin SIL wirewrap connector with 13mm tin plated brass terminations.

- **Preci-dip type 323-87-1xx-41-001** where xx is no. of pins
- Available in **strips of 20 or 32-ways** which may be cut easily to required number of ways



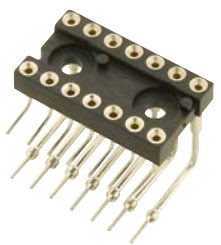
Type	Order code	1+	50+	250+
20-pin Connector	22-1710	0.99	0.8528	0.728
32-pin Connector	22-1711	1.51	1.35	1.20



DIL Display sockets

Right angled dual in line sockets for mounting LED displays or similar components onto PCBs.

- 7.62mm (0.3in) pitch
- Fitted with 0.25µ gold plated contacts
- **Preci-dip 299** series



Type	Pitch	Order code	1+	50+	250+
14-way	0.3in	22-1700	1.40	1.27	1.14
20-way	0.3in	22-1701	1.25		

Grab yourself a deal

See our clearance section
www.rapidonline.com/clearance

To save time

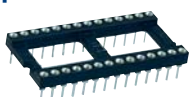
Fax any of your previous bulk orders for our quote to:
01206 751188

TruConnect

Low profile turned pin DIL sockets

Low profile high-quality machined contact DIL sockets. Each socket is fitted with precision two-part sockets consisting of a four fingered gold over nickel plated beryllium-copper inner contact with a tin plated brass outer shell.

- Moulded in black glass-filled flame retardant polyester
- Height above PCB 4.3mm
- Available either **singularly** or in **tube quantities**



Technical specification	
Insulator material	Glass filled polyester
Contact material	Rated UL94V-0
Contact material	4 finger gold plated beryllium copper
inner	Tin plated brass
outer	1A
Current rating	10mΩ max.
Contact resistance	1 x 109Ω min.
Insulation resistance	1000V
Dielectric strength	-55°C to +125°C
Operating temperature	

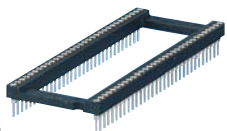
Price each					
Type	Pitch	Order code	1+	50+	250+
8-pin	0.3in	22-1720	0.15	0.1144	0.0936
14-pin	0.3in	22-1721	0.36	0.2808	0.2184
16-pin	0.3in	22-1722	0.41	0.3016	0.26
18-pin	0.3in	22-1723	0.47	0.3536	0.2808
20-pin	0.3in	22-1724	0.35	0.2704	0.2288
24-pin	0.3in	22-1725	0.41	0.32	0.27
28-pin	0.3in	22-1726	0.49	0.3852	0.312
24-pin	0.6in	22-1727	0.42	0.3224	0.2704
28-pin	0.6in	22-1728	0.48	0.39	0.31
32-pin	0.6in	22-1729	0.56	0.41	0.36
40-pin	0.6in	22-1730	0.71	0.572	0.4472

TruConnect

Shrink-DIP socket

High reliability low profile IC socket with high density contacts on 0.07in (1.778mm) lead spacing.

- Four finger beryllium copper contact meets high vibration and shock requirements



Technical specification	
Contact material	Beryllium copper
Contact plating	0.25µ gold over nickel
Insulator material	Glass filled polyester (UL94V-0 rated)
Operating temperature	-55° to +125°C
Mfrs. part no.	117-87-764-41-005

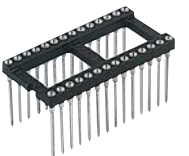
Type	Order code	1+
64-way Shrink-DIP	22-1706	1.25

TruConnect

Wirewrap turned pin DIL sockets

Professional quality turned pin wirewrap sockets with 13mm tin plated brass terminations to allow three wraps per pin.

- Four finger gold plated (0.25 micron) inner contacts
- Technical specification as for low profile type **22-1720**
- Moulded in black glass-filled flame retardant polyester
- Height above PCB 4.9mm
- **Preci-dip type 123-87-3xx-41001** where xx is no. of pins

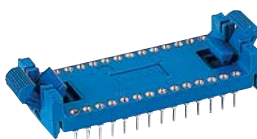


Type	Pitch	Order code	1+	50+	250+
8-pin	0.3in	22-1715	0.41	0.3536	0.312
14-pin	0.3in	22-1716	0.62	0.55	0.46
16-pin	0.3in	22-1717	0.67	0.61	0.53
18-pin	0.3in	22-1718	0.75	0.6968	0.6032
28-pin	0.3in	22-1719	1.13	1.05	0.91
40-pin	0.3in	22-0250	1.55	1.32	1.13

Aries
Lock/eject DIL sockets

DIL sockets specifically designed for fast in-field board maintenance.

- Latches act as a locking device to prevent disconnection
- The latches also act as ejectors of the IC
- Turned pin contacts
- 0.6in row spacing on a 0.1in pitch



Technical specification		Beryllium copper
Contact material		Gold-on-nickel
Contact plating		Glass filled thermoplastic, UL94V-0 rated
Insulator material		-55°C to +105°C
Temperature range		xx-C182-10
Manufacturers part no.		where xx = no. of ways

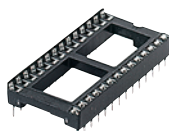
Type	Order code	1+	25+	100+	250+
28-pin	22-1525	4.88	4.12	3.85	3.59
40-pin	22-1535	6.71	5.67	5.25	4.94

TruConnect

Low profile DIL IC sockets

Cost effective high quality low profile DIL socket with dual wipe contacts providing maximum contact retention at minimum cost.

- End and side stackable for high density circuit layouts
- Body moulding is in black glass-filled polyester
- TruConnect type **TS1001-xx** where xx is no. of pins
- Available **singly** and in **tubes**



Technical specification			
Type	Pitch (in (mm))	Length (mm)	Width (mm)
6-pin	0.3 (7.62)	7.48	10.02
Height (mm)	5.1		
Insulator material			
30% glass filled PBT			
Rated UL94V-0			
Contact material			
5191 phosphor bronze			
Contact plating			
Tin			
Current rating			
1A max.			
Contact resistance			
200mΩ max.			
Insulation resistance			
5 x 10 ⁹ Ω at 500V DC			
Insertion force			
340g max. per contact			
Withdrawal force			
14g min. per contact			
Operating temperature			
-55°C to +105°C			

Type	Order code	1+	5+	10+	25+
6-pin (tube of 80)	22-0130	2.45	2.38	2.20	1.95

Aries
Universal ZIF sockets



A comprehensive range of ZIF sockets which will accept either 0.3, 0.4 or 0.6 inch row spacing with pin widths of 0.38 to 1.15mm.

- Single positive lever locking mechanism with lever down for ON position

Technical specification		Beryllium copper
Contact material		Tin
Contact plating		Polypropylene sulphide, UL94V-0 rated
Insulator material		0.1in
Pin spacing		0.3 to 0.6in
IC row spacing		0.6in
PCB row spacing		1A
Contact rating		25,000 cycles (min.)
Life		xx-6594-10 where xx = no. of pins
Manufacturers part no.		

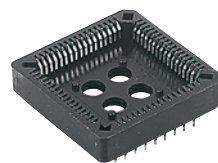
Type	Order code	1+	10+	25+
24-pin	22-1560	8.93	7.58	7.32
28-pin	22-1565	10.35	8.74	8.42
32-pin	22-1570	11.39	9.78	9.46
40-pin	22-1580	13.47	11.44	11.13

TruConnect

Production PLCC sockets

Very competitively priced sockets for JEDEC plastic plastic leaded chip carrier packages with industry standard pinouts.

- Heat resistant PBT resin
- The contact design prevents the IC from vibrating loose
- Closed beryllium-copper alloy contacts
- Tin plated
- 2.54mm pitch
- Twin slots are provided for easy extraction of the IC



Technical specification			
Type	Order code	Length	Height
28-way	22-0340	18	7.7
32-way	22-0345	18.05	7.7
44-way	22-0350	24.5	7.7
52-way	22-0355	27	7.7
68-way	22-0360	32	7.7
84-way	22-0365	37	7.7

Type	Order code	1+	10+	50+	500+
28-way PLCC Socket	22-0340	0.45	0.364	0.312	0.2527
32-way PLCC Socket	22-0345	0.47	0.3952	0.2985	0.2205
44-way PLCC Socket	22-0350	0.40	0.3328	0.2756	0.2288
52-way PLCC Socket	22-0355	0.52	0.4472	0.364	0.2985
68-way PLCC Socket	22-0360	0.46	0.3848	0.312	0.26
84-way PLCC Socket	22-0365	0.67	0.5512	0.4545	0.39



Production PLCC sockets

A range of competitive PLCC sockets from AMP for JEDEC pattern industry standard chip carrier packages.

- Tin plated phosphor bronze contacts
- 2.54mm pitch



Type	Order code	1+	10+	50+
32-way	22-4702	0.93	0.8528	0.7904
44-way	22-4704	1.03	0.884	0.8216
68-way	22-4708	1.12	0.9464	0.884
84-way	22-4710	1.18	0.9984	0.9256

TruConnect

SMT Low profile PLCC sockets



- A range of low profile surface mount PL CC sockets.
- Surface mount design
- Design prevents the IC from vibrating loose
- 2.54mm pitch
- Very low profile
- Twin slots are provided for easy extraction of the IC

Technical specification		Phosphor bronze
Contact material		Tin
Contact plating		40% glass filled PPS (rated UL94V-0)
Insulator material		-50°C to +105°C
Operating temperature		

Dimensions (mm)		Length	Height
20-way		15.65	4.65
32-way		18.23	4.65
44-way		23.28	4.65
68-way		30.95	4.65

Type	Order code	1+	50+	500+	2000+
20-way	72-7600	0.55	0.4472	0.3765	0.3567
32-way	72-7610	0.51	0.4056	0.3224	0.2964
44-way	72-7615	0.55	0.4576	0.364	0.312
68-way	72-7625	0.80	0.6032	0.468	0.4025

RVFM**PLCC Extraction tool**

A spring assisted chip carrier extraction tool that has been specifically designed for the safe and fast removal of PLCCs from sockets (through hole or SMT) without damage to component parts.

- Constructed from hardened steel



Type	Order code	1+	10+	25+
PLCC Extraction tool	22-0395	4.13	3.50	3.02

RVFM**IC Extraction tool**

A simple and handy spring clip tool for easy extraction of integrated circuits.

- Suitable for use with ICs with up to 40-pins
- Insulated handle



Type	Order code	1+	25+
IC Extraction tool	22-0321	0.79	0.64

TruSemi**IC Straightener**

A double-sided IC straightener which will work with 8-pin to 48-pin ICs.

- Anti-static ground terminal
- Narrow side for 8/14/16/18/20 pin ICs - wide side for 24/28/40/42/48 pin ICs
- Ideal for the constant reuse of ICs

Type	Order code	1+	25+	100+
IC Straightener	22-0330	2.99	2.56	2.42

RVFM**IC Extraction/insertion tool**

A high quality spring loaded tool.

- Suitable for use with 0.3in (8, 14, 16, 18 and 20-pin) devices



Type	Order code	1+	25+	100+
IC Insertion tool	22-0325	1.35	1.17	1.09

Page 711

Heavy duty footswitches (with guards)

Die-cast units that are available with snap action or slow action contact blocks.



- Snap action or slow action contact blocks
- Self-rising saddle-washer terminal connections
- Single or double pole contact blocks
- Positive opening operations
- Silver contacts
- Anti-slip foot pedal
- Non-slip rubber feet



Type	Actuating force
A 1 snap action contact block	10N
B 1 slow action contact block	12N
C 2 snap action contact blocks	13N
D 2 slow action contact blocks	15N

Order code	FROM
A 78-3792	26.49
B 78-3794	25.69
C 78-3796	26.89
D 78-3798	25.99

**Your first click for components**

- **Convenient Product Search**

Search by Rapid order code or by keyword description using auto-suggest search. Advanced search allows searching within a product category.

- **Secure Online Purchasing**

The latest SSL encryption ensures all your transactions and personal details are held securely.

- **Same Day Despatch**

Online orders placed between 8am-8pm Monday to Friday will be despatched the same day.

Spend over £30 (excl. VAT) and delivery is **FREE*** - Excluding any timed delivery charge.

*UK mainland only.

- **Extended Despatch Service**

All online orders received between Friday 8pm and Saturday 5pm are shipped on Saturday†.

†Weight and value restrictions apply.

www.rapidonline.com

5 Easy ways to order

The fastest & easiest way to order is **ONLINE** 24 hours a day!

**www.rapidonline.com**

- Quick order form
- Save paper ... go green
- Track your order online
- Ability to pay by credit/debit card or on account
- Live help
- Transaction history

**sales@rapidelec.co.uk****Orderline 01206 751166**

General enquiries **01206 835577**
(Between 8.00am and 8.00pm, Monday to Friday, 9.00am to 5.00pm Saturday)

**01206 751188**

**Rapid, Severalls Lane,
Colchester, Essex CO4 5JS**

